

Layered board for copper@ printed circuit boards - including unit layers composed of glass non-woven fabric impregnated with polyepoxy resin and inorganic filler e.g. graphite, etc., carbon@ PCB

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Abstract (Basic): JP 7176843 A

In a layered board for a printed circuit produced by preparing unit resin impregnation layer each composed of a glass non-woven fabric impregnated with epoxy resin and inorganic filler, then layering the unit resin impregnation layers with application of heat and pressure, the content of the inorganic filler is 10-200 pts.wt. - 100 pts.wt. of the resin, and the ratio of the length to the thickness of the filler is in range of 5.0-200.

USE/ADVANTAGE - Suitable for a copper-layered printed circuit board. The layered board has good dimensional accuracy, drill workability and punching workability.

The epoxy resin is e.g. brominated epoxy resin, non-brominated epoxy resin, bisphenol A type epoxy resin or novolak type epoxy resin etc.. The inorganic filler e.g. consists of mica, graphite or wollastonite, etc..

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Title Terms: LAYER; BOARD; COPPER; PRINT; CIRCUIT; BOARD; UNIT; LAYER; COMPOSE; GLASS; NON; WOVEN; FABRIC; IMPREGNATE; POLYEPOXIDE; RESIN; INORGANIC; FILL; GRAPHITE; CARBON; PCB

Derwent Class: A21; A85; L03; P73; V04

International Patent Class (Main): H05K-001/03

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